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(54) PRIMER COMPOSITION AND ELECTRIC/ELECTRONIC COMPONENT USING THE SAME

(57)Abstract:
PROBLEM TO BE SOLVED: To provide a primer composition which strongly bonds a high-hardness silicone resin used as a protective layer of an electric/electronic element to adherends being an element and a substrate and can be used for producing a highly reliable electric/electronic component; and an electric/electronic component using the composition.
SOLUTION: The primer composition contains an organosiloxane oligomer (A) and a diluent (B) as essential ingredients. The organosiloxane oligomer (A) is represented by the formula (1): R1aR2bR3cR4d(OR5)eSiO(4-a-b-c-d-e)/2 (wherein R1 is an epoxide-containing monovalent organic group; R2 is a monovalent hydrocarbon group containing a non-conjugated double bond; R3 is a monovalent organic group containing a (meth)acrylic functional group; R4 is a hydrogen atom or a monovalent hydrocarbon group; R5 is a hydrogen atom or a monovalent hydrocarbon group; $0.2 \leq a \leq 0.9$; $0.1 \leq b \leq 0.6$; $0 \leq c \leq 0.6$; $0 \leq d \leq 0.8$; $1.0 \leq e \leq 2.0$; and $2.0 \leq a+b+c+d+e \leq 3.0$) and contains 2.0 ppm or less ionic impurities (Na, K, Cl).